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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16lc622at-04-ss">https://www.e-xfl.com/product-detail/microchip-technology/pic16lc622at-04-ss</a>

## 2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

### 2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the Oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

<b>Note:</b> Microchip does not recommend code protecting windowed devices.
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### 2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

### 2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP programming service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices, but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

### 2.4 Serialized Quick-Turnaround-Production<sup>SM</sup> (SQTP<sup>SM</sup>) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number, which can serve as an entry-code, password or ID number.

## 4.2.2.2 OPTION Register

The OPTION register is a readable and writable register, which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

**Note:** To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

### REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

- bit 7 **RBPU: PORTB Pull-up Enable bit**  
 1 = PORTB pull-ups are disabled  
 0 = PORTB pull-ups are enabled by individual port latch values
- bit 6 **INTEDG: Interrupt Edge Select bit**  
 1 = Interrupt on rising edge of RB0/INT pin  
 0 = Interrupt on falling edge of RB0/INT pin
- bit 5 **T0CS: TMR0 Clock Source Select bit**  
 1 = Transition on RA4/T0CKI pin  
 0 = Internal instruction cycle clock (CLKOUT)
- bit 4 **T0SE: TMR0 Source Edge Select bit**  
 1 = Increment on high-to-low transition on RA4/T0CKI pin  
 0 = Increment on low-to-high transition on RA4/T0CKI pin
- bit 3 **PSA: Prescaler Assignment bit**  
 1 = Prescaler is assigned to the WDT  
 0 = Prescaler is assigned to the Timer0 module
- bit 2-0 **PS<2:0>: Prescaler Rate Select bits**

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

#### Legend:

R = Readable bit      W = Writable bit      U = Unimplemented bit, read as '0'  
 - n = Value at POR      '1' = Bit is set      '0' = Bit is cleared      x = Bit is unknown

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## 4.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for all interrupt sources except the comparator module. See Section 4.2.2.4 and Section 4.2.2.5 for a description of the comparator enable and flag bits.

**Note:** Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

### REGISTER 4-3: INTCON REGISTER (ADDRESS 0BH OR 8BH)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF
bit 7							bit 0

- bit 7 **GIE:** Global Interrupt Enable bit  
1 = Enables all un-masked interrupts  
0 = Disables all interrupts
- bit 6 **PEIE:** Peripheral Interrupt Enable bit  
1 = Enables all un-masked peripheral interrupts  
0 = Disables all peripheral interrupts
- bit 5 **TOIE:** TMR0 Overflow Interrupt Enable bit  
1 = Enables the TMR0 interrupt  
0 = Disables the TMR0 interrupt
- bit 4 **INTE:** RB0/INT External Interrupt Enable bit  
1 = Enables the RB0/INT external interrupt  
0 = Disables the RB0/INT external interrupt
- bit 3 **RBIE:** RB Port Change Interrupt Enable bit  
1 = Enables the RB port change interrupt  
0 = Disables the RB port change interrupt
- bit 2 **TOIF:** TMR0 Overflow Interrupt Flag bit  
1 = TMR0 register has overflowed (must be cleared in software)  
0 = TMR0 register did not overflow
- bit 1 **INTF:** RB0/INT External Interrupt Flag bit  
1 = The RB0/INT external interrupt occurred (must be cleared in software)  
0 = The RB0/INT external interrupt did not occur
- bit 0 **RBIF:** RB Port Change Interrupt Flag bit  
1 = When at least one of the RB<7:4> pins changed state (must be cleared in software)  
0 = None of the RB<7:4> pins have changed state

#### Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared    x = Bit is unknown

## 5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

### 5.1 PORTA and TRISA Registers

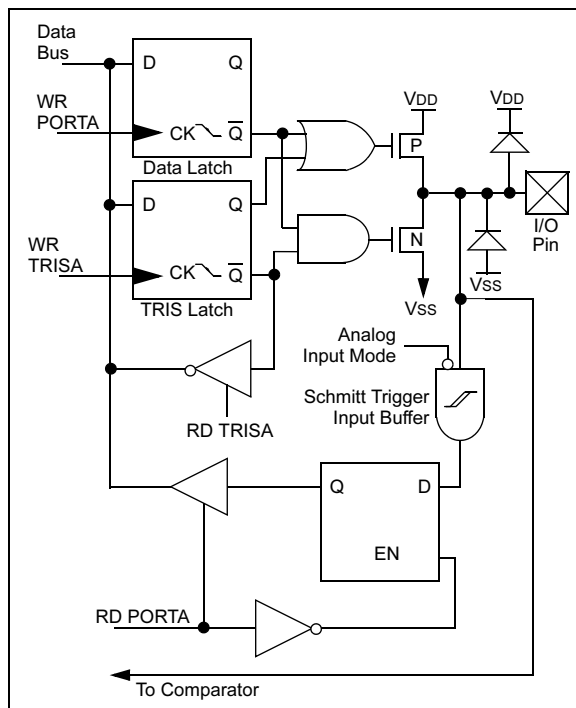
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

**FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS**



**Note:** On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

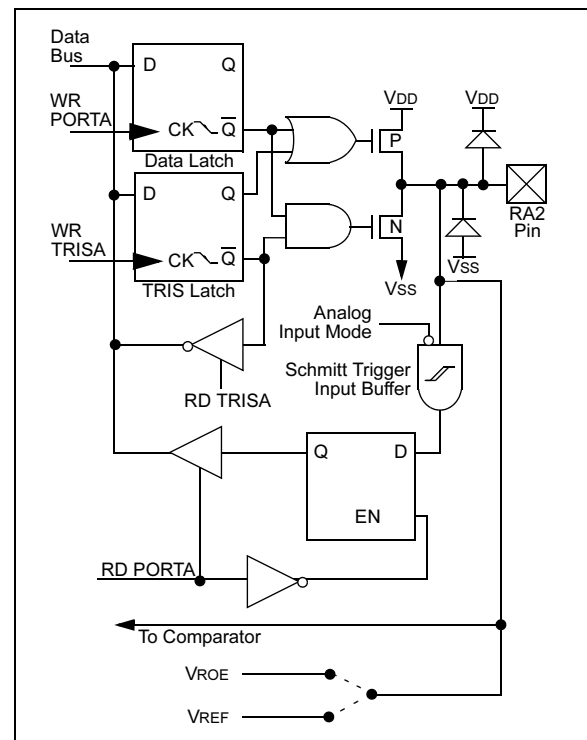
The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

**EXAMPLE 5-1: INITIALIZING PORTA**

```
CLRF    PORTA      ;Initialize PORTA by setting
                   ;output data latches
MOVLW   0X07       ;Turn comparators off and
MOVWF    CMCON      ;enable pins for I/O
                   ;functions
BSF      STATUS, RP0 ;Select Bank1
MOVLW   0x1F       ;Value used to initialize
                   ;data direction
MOVWF    TRISA      ;Set RA<4:0> as inputs
                   ;TRISA<7:5> are always
                   ;read as '0'.
```

**FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN**



## 5.3 I/O Programming Considerations

### 5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The `BCF` and `BSF` instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a `BSF` operation on bit5 of `PORTB` will cause all eight bits of `PORTB` to be read into the CPU. Then the `BSF` operation takes place on bit5 and `PORTB` is written to the output latches. If another bit of `PORTB` is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Reading the port register reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. `BCF`, `BSF`, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (ex., `BCF`, `BSF`, etc.) on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

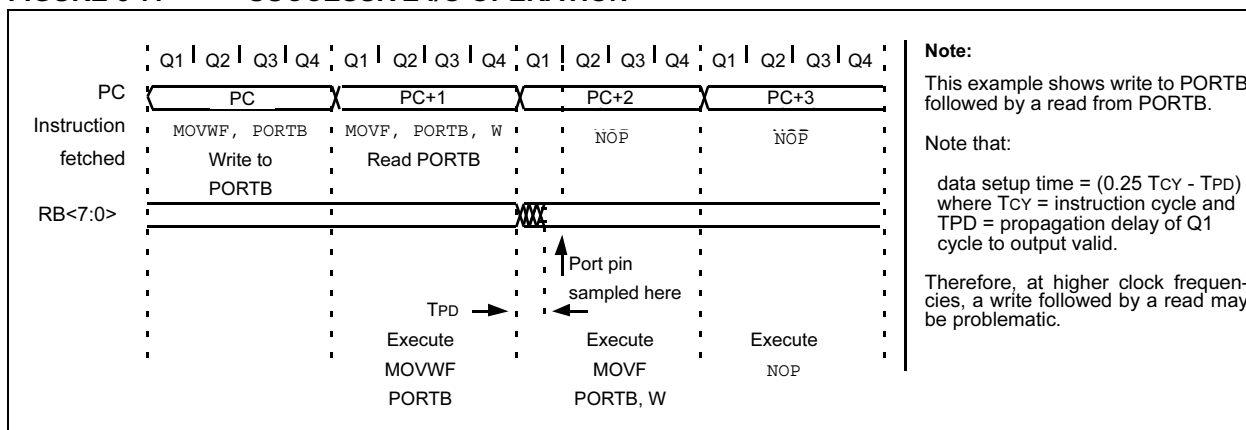
### EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
; Initial PORT settings:   PORTB<7:4> Inputs
;
;                           PORTB<3:0> Outputs
; PORTB<7:6> have external pull-up and are not
; connected to other circuitry
;
;                           PORT latch  PORT pins
;                           -----
;
;
; BCF PORTB, 7             ; 01pp pppp   11pp pppp
; BCF PORTB, 6             ; 10pp pppp   11pp pppp
; BSF STATUS,RP0           ;
; BCF TRISB, 7             ; 10pp pppp   11pp pppp
; BCF TRISB, 6             ; 10pp pppp   10pp pppp
;
; Note that the user may have expected the pin
; values to be 00pp pppp. The 2nd BCF caused
; RB7 to be latched as the pin value (High).
```

### 5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a `NOP` or another instruction not accessing this I/O port.

FIGURE 5-7: SUCCESSIVE I/O OPERATION



## 6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on-the-fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

### EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

```

1.BCF      STATUS, RP0    ;Skip if already in
                           ;Bank 0
2.CLRWDT                      ;Clear WDT
3.CLRF      TMR0          ;Clear TMR0 & Prescaler
4.BSF      STATUS, RP0    ;Bank 1
5.MOVLW     '00101111'b;  ;These 3 lines (5, 6, 7)
6.MOVWF     OPTION        ;are required only if
                           ;desired PS<2:0> are
7.CLRWDT                      ;000 or 001
8.MOVLW     '00101xxx'b   ;Set Postscaler to
9.MOVWF     OPTION        ;desired WDT rate
10.BCF      STATUS, RP0    ;Return to Bank 0
    
```

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

### EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```

CLRWDT                      ;Clear WDT and
                           ;prescaler
BSF      STATUS, RP0
MOVLW     b'xxxx0xxx'      ;Select TMR0, new
                           ;prescale value and
                           ;clock source
MOVWF     OPTION_REG
BCF      STATUS, RP0
    
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0 module register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

**Note:** Shaded bits are not used by TMR0 module.

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## 7.4 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise the maximum delay of the comparators should be used (Table 12-2).

## 7.5 Comparator Outputs

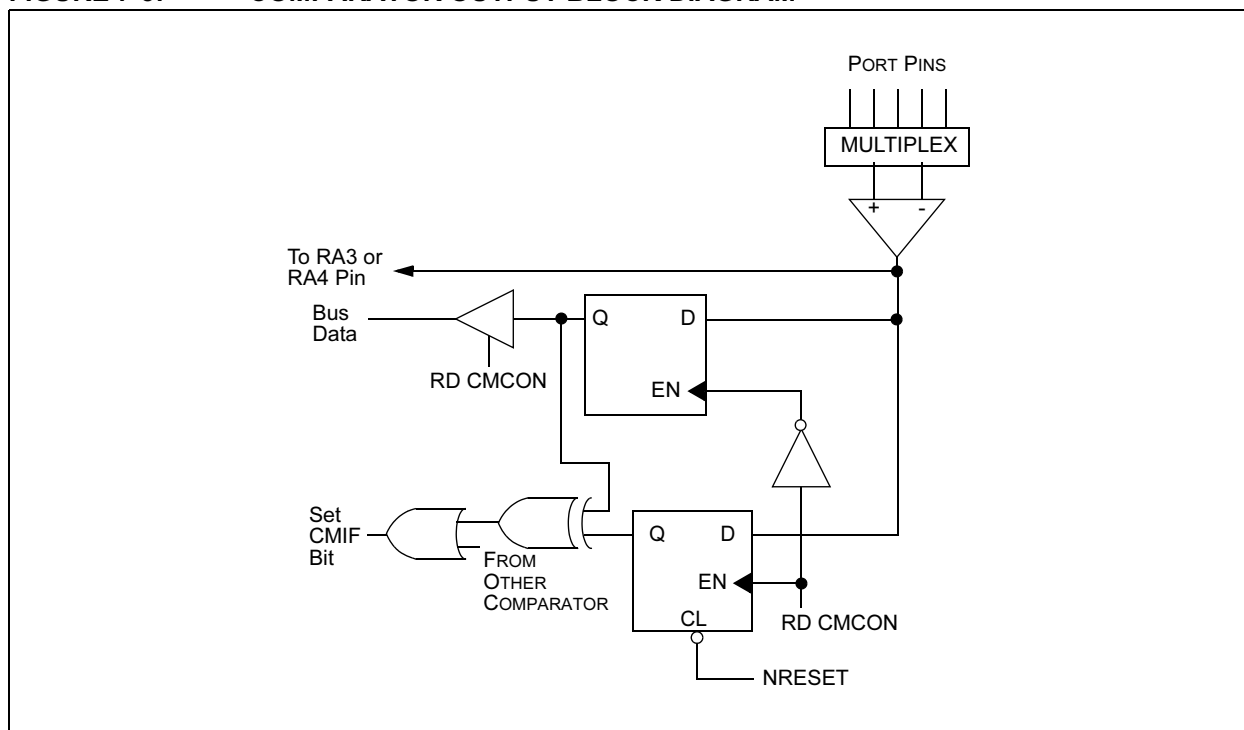
The comparator outputs are read through the CMCON register. These bits are read only. The comparator outputs may also be directly output to the RA3 and RA4 I/O pins. When the CM<2:0> = 110, multiplexors in the output path of the RA3 and RA4 pins will switch and the output of each pin will be the unsynchronized output of the comparator. The uncertainty of each of the comparators is related to the input offset voltage and the response time given in the specifications. Figure 7-3 shows the comparator output block diagram.

The TRISA bits will still function as an output enable/disable for the RA3 and RA4 pins while in this mode.

**Note 1:** When reading the PORT register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the Schmitt Trigger input specification.

**2:** Analog levels on any pin that is defined as a digital input may cause the input buffer to consume more current than is specified.

FIGURE 7-3: COMPARATOR OUTPUT BLOCK DIAGRAM





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## EXAMPLE 8-1: VOLTAGE REFERENCE CONFIGURATION

MOVLW	0x02	; 4 Inputs Muxed
MOVWF	CMCON	; to 2 comps.
BSF	STATUS,RP0	; go to Bank 1
MOVLW	0x0F	; RA3-RA0 are
MOVWF	TRISA	; inputs
MOVLW	0xA6	; enable VREF
MOVWF	VRCON	; low range
		; set VR<3:0>=6
BCF	STATUS,RP0	; go to Bank 0
CALL	DELAY10	; 10 $\mu$ s delay

## 8.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 8-1) keep VREF from approaching VSS or VDD. The voltage reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The tested absolute accuracy of the voltage reference can be found in Table 12-2.

## 8.3 Operation During SLEEP

When the device wakes up from SLEEP through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the voltage reference should be disabled.

## 8.4 Effects of a RESET

A device RESET disables the voltage reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

## 8.5 Connection Considerations

The voltage reference module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the voltage reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the voltage reference output for external connections to VREF. Figure 8-2 shows an example buffering technique.

FIGURE 8-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE

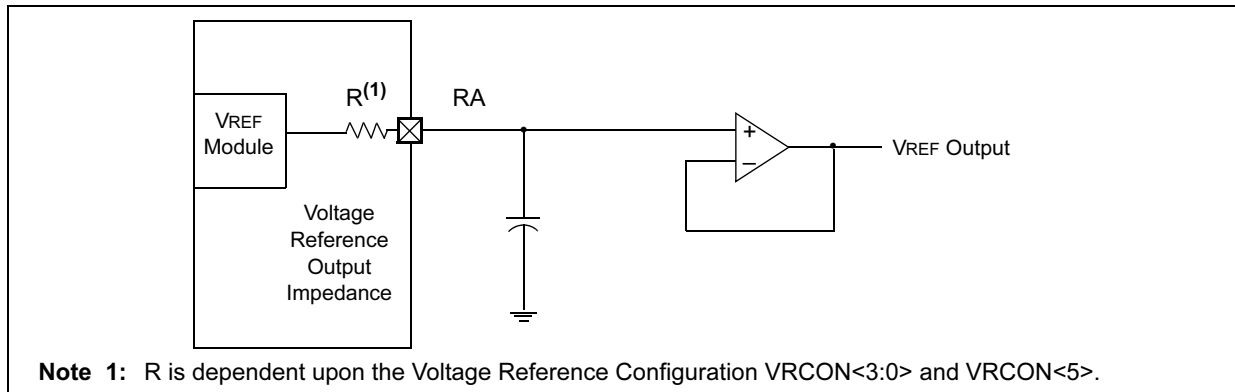


TABLE 8-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR	Value On All Other RESETS
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

**Note:** - = Unimplemented, read as "0"

## 9.3 RESET

The PIC16C62X differentiates between various kinds of RESET:

- Power-on Reset (POR)
- $\overline{\text{MCLR}}$  Reset during normal operation
- $\overline{\text{MCLR}}$  Reset during SLEEP
- WDT Reset (normal operation)
- WDT wake-up (SLEEP)
- Brown-out Reset (BOR)

Some registers are not affected in any RESET condition. Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset,

$\overline{\text{MCLR}}$  Reset, WDT Reset and  $\overline{\text{MCLR}}$  Reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation.  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  bits are set or cleared differently in different RESET situations as indicated in Table 9-2. These bits are used in software to determine the nature of the RESET. See Table 9-5 for a full description of RESET states of all registers.

A simplified block diagram of the on-chip RESET circuit is shown in Figure 9-6.

The  $\overline{\text{MCLR}}$  Reset path has a noise filter to detect and ignore small pulses. See Table 12-5 for pulse width specification.

**FIGURE 9-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT**

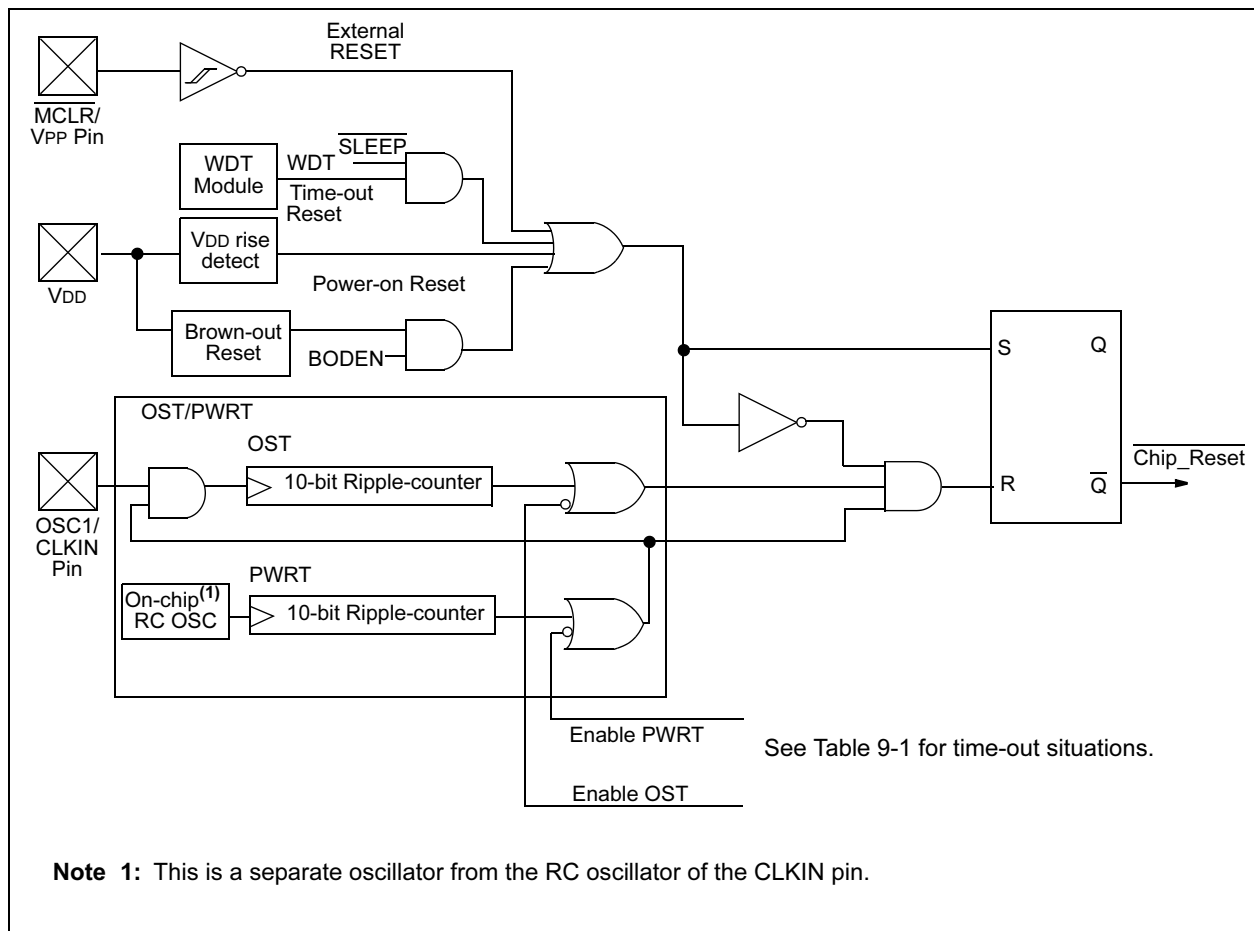


FIGURE 9-8: TIME-OUT SEQUENCE ON POWER-UP ( $\overline{\text{MCLR}}$  NOT TIED TO  $V_{DD}$ ): CASE 1

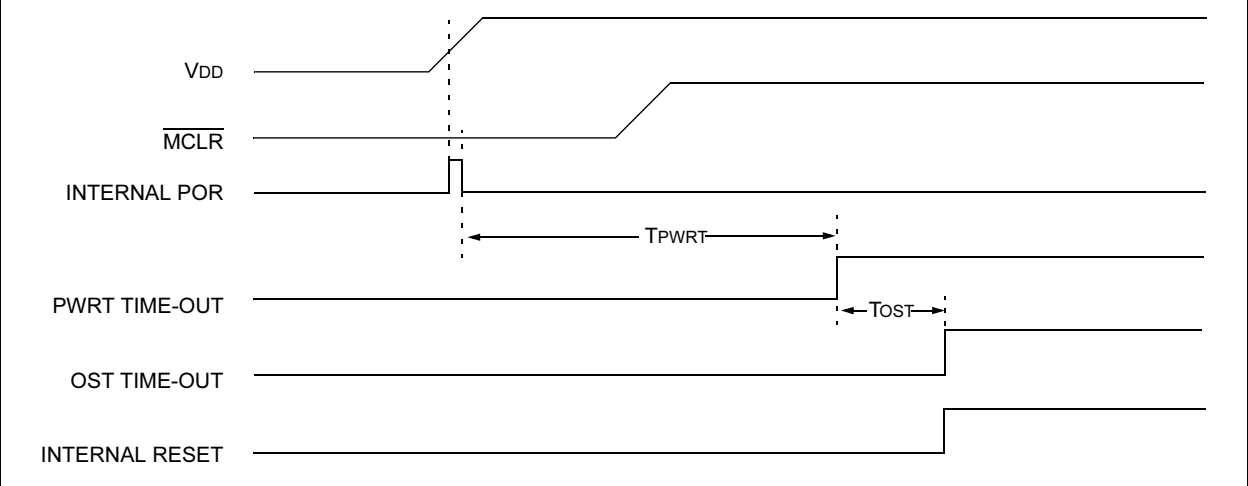


FIGURE 9-9: TIME-OUT SEQUENCE ON POWER-UP ( $\overline{\text{MCLR}}$  NOT TIED TO  $V_{DD}$ ): CASE 2

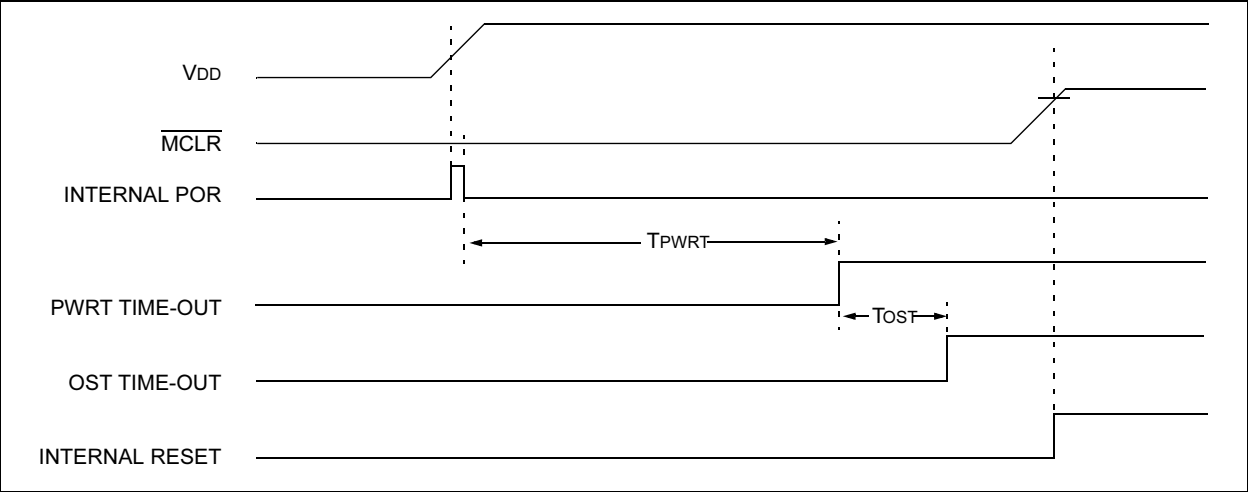
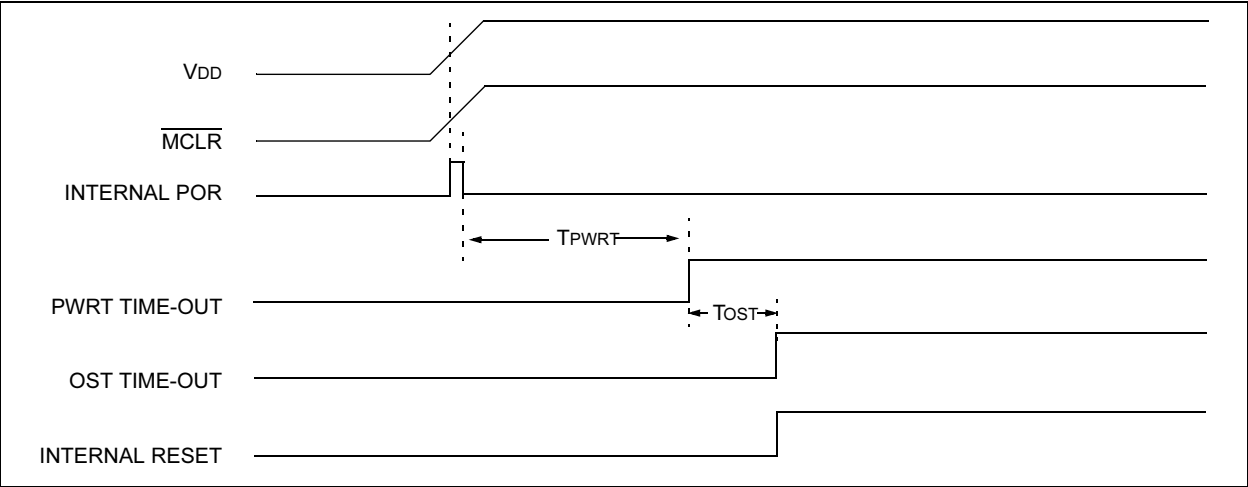


FIGURE 9-10: TIME-OUT SEQUENCE ON POWER-UP ( $\overline{\text{MCLR}}$  TIED TO  $V_{DD}$ )



**TABLE 9-6: SUMMARY OF INTERRUPT REGISTERS**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS <sup>(1)</sup>
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----

**Note 1:** Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

## 9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and STATUS register). This will have to be implemented in software.

Example 9-3 stores and restores the STATUS and W registers. The user register, W\_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W\_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS\_TEMP, must be defined in Bank 0. The Example 9-3:

- Stores the W register
- Stores the STATUS register in Bank 0
- Executes the ISR code
- Restores the STATUS (and bank select bit register)
- Restores the W register

### EXAMPLE 9-3: SAVING THE STATUS AND W REGISTERS IN RAM

```

MOVWF  W_TEMP      ;copy W to temp register,
                    ;could be in either bank
SWAPF  STATUS,W     ;swap status to be saved
                    ;into W
BCF    STATUS,RP0    ;change to bank 0 regardless
                    ;of current bank
MOVWF  STATUS_TEMP  ;save status to bank 0
                    ;register
:
:    (ISR)
:
SWAPF  STATUS_TEMP, W ;swap STATUS_TEMP register
                    ;into W, sets bank to origi-
                    ;nal
                    ;state
MOVWF  STATUS        ;move W into STATUS register
SWAPF  W_TEMP,F      ;swap W_TEMP
SWAPF  W_TEMP,W      ;swap W_TEMP into W

```

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NOTES:

## 11.9 MPLAB ICE 2000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 2000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers. Software control of the MPLAB ICE 2000 in-circuit emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE 2000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft® Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

## 11.10 MPLAB ICE 4000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 4000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for high-end PICmicro microcontrollers. Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 4000 is a premium emulator system, providing the features of MPLAB ICE 2000, but with increased emulation memory and high speed performance for dsPIC30F and PIC18XXXX devices. Its advanced emulator features include complex triggering and timing, up to 2 Mb of emulation memory, and the ability to view variables in real-time.

The MPLAB ICE 4000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

## 11.11 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low cost, run-time development tool, connecting to the host PC via an RS-232 or high speed USB interface. This tool is based on the FLASH PICmicro MCUs and can be used to develop for these and other PICmicro microcontrollers. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ (ICSP™) protocol, offers cost effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single-stepping and watching variables, CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real-time. MPLAB ICD 2 also serves as a development programmer for selected PICmicro devices.

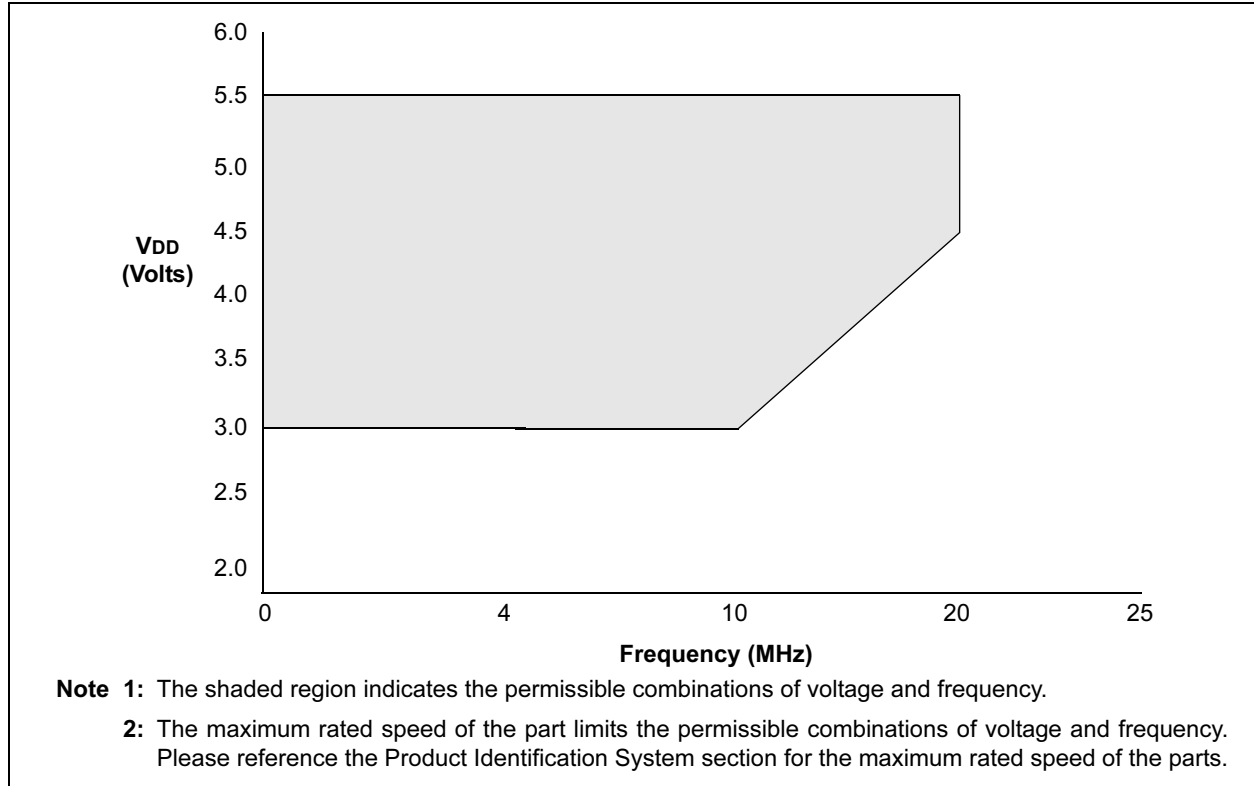
## 11.12 PRO MATE II Universal Device Programmer

The PRO MATE II is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features an LCD display for instructions and error messages and a modular detachable socket assembly to support various package types. In Stand-Alone mode, the PRO MATE II device programmer can read, verify, and program PICmicro devices without a PC connection. It can also set code protection in this mode.

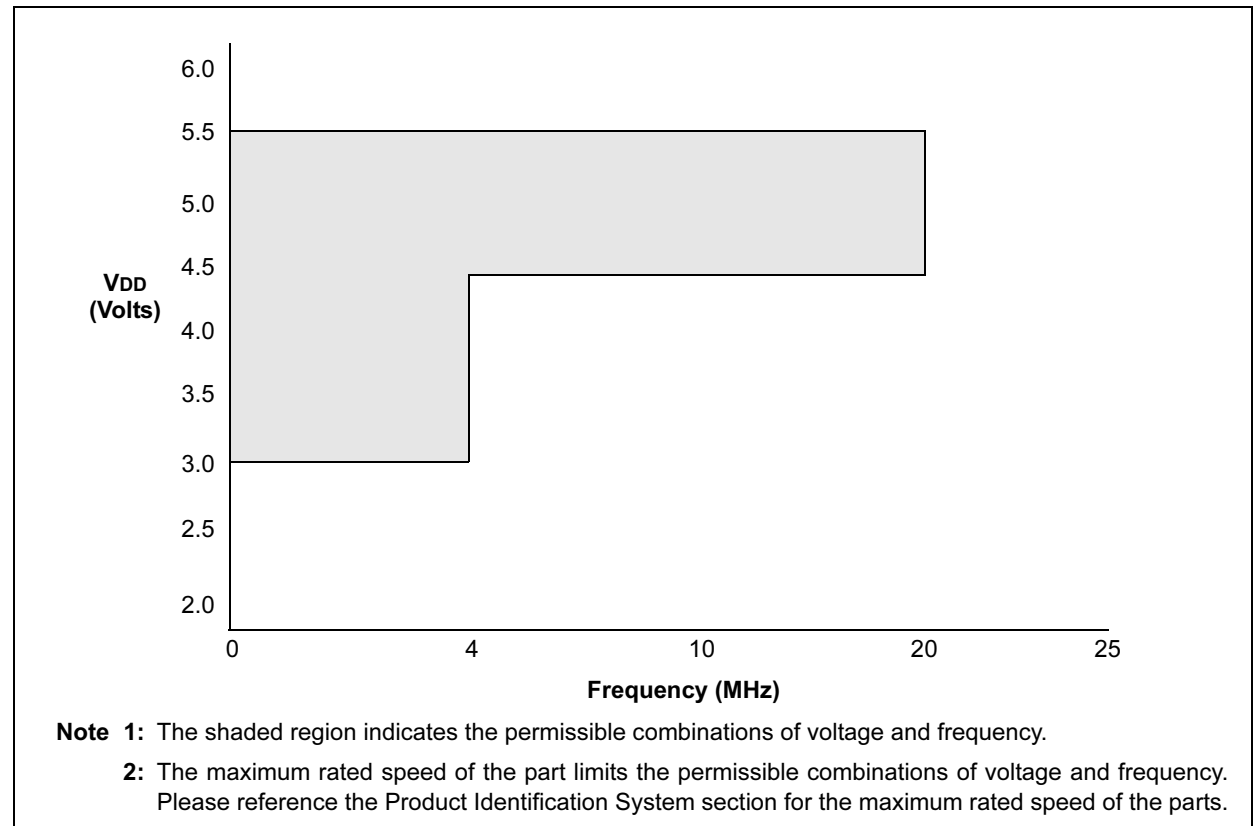
## 11.13 PICSTART Plus Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus development programmer supports most PICmicro devices up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

**FIGURE 12-7: PIC16CR62XA VOLTAGE-FREQUENCY GRAPH,  $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$**



**FIGURE 12-8: PIC16CR62XA VOLTAGE-FREQUENCY GRAPH,  $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$ ,  $+70^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$**



## 12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage $V_{DD}$ range is the PIC16C62X range.					
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D022	$\Delta I_{WDT}$	WDT Current <sup>(5)</sup>	—	6.0	20	$\mu\text{A}$	$V_{DD}=4.0\text{V}$ (125°C)
D022A	$\Delta I_{BOR}$	Brown-out Reset Current <sup>(5)</sup>	—	350	425	$\mu\text{A}$	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	$\Delta I_{COMP}$	Comparator Current for each Comparator <sup>(5)</sup>	—	—	100	$\mu\text{A}$	$V_{DD} = 4.0\text{V}$
D023A	$\Delta I_{VREF}$	VREF Current <sup>(5)</sup>	—	—	300	$\mu\text{A}$	$V_{DD} = 4.0\text{V}$
D022	$\Delta I_{WDT}$	WDT Current <sup>(5)</sup>	—	6.0	15	$\mu\text{A}$	$V_{DD}=3.0\text{V}$
D022A	$\Delta I_{BOR}$	Brown-out Reset Current <sup>(5)</sup>	—	350	425	$\mu\text{A}$	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	$\Delta I_{COMP}$	Comparator Current for each Comparator <sup>(5)</sup>	—	—	100	$\mu\text{A}$	$V_{DD} = 3.0\text{V}$
D023A	$\Delta I_{VREF}$	VREF Current <sup>(5)</sup>	—	—	300	$\mu\text{A}$	$V_{DD} = 3.0\text{V}$
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** This is the limit to which  $V_{DD}$  can be lowered without losing RAM data.

**2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all  $I_{DD}$  measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to  $V_{DD}$ ,

MCLR =  $V_{DD}$ ; WDT enabled/disabled as specified.

**3:** The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to  $V_{DD}$  or  $V_{SS}$ .

**4:** For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula:  $I_r = V_{DD}/2R_{EXT}$  (mA) with  $R_{EXT}$  in k $\Omega$ .

**5:** The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base  $I_{DD}$  or  $I_{PD}$  measurement.



## 12.6 DC Characteristics: PIC16C620A/C621A/C622A-40<sup>(3)</sup> (Commercial) PIC16CR620A-40<sup>(3)</sup> (Commercial)

DC CHARACTERISTICS Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	Sym	Min	Typ <sup>(1)</sup>	Max	Units	Conditions
Supply Voltage	VDD	4.5	—	5.5	V	HS Option from 20 - 40 MHz
Supply Current <sup>(2)</sup>	IDD	—	5.5 7.7	11.5 16	mA mA	FOSC = 40 MHz, VDD = 4.5V, HS mode FOSC = 40 MHz, VDD = 5.5V, HS mode
HS Oscillator Operating Frequency	FOSC	20	—	40	MHz	OSC1 pin is externally driven, OSC2 pin not connected
Input Low Voltage OSC1	VIL	VSS	—	0.2VDD	V	HS mode, OSC1 externally driven
Input High Voltage OSC1	VIH	0.8VDD	—	VDD	V	HS mode, OSC1 externally driven

\* These parameters are characterized but not tested.

**Note 1:** Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

**2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS,  
T0CKI = VDD, MCLR = VDD; WDT disabled, HS mode with OSC2 not connected.

**3:** For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

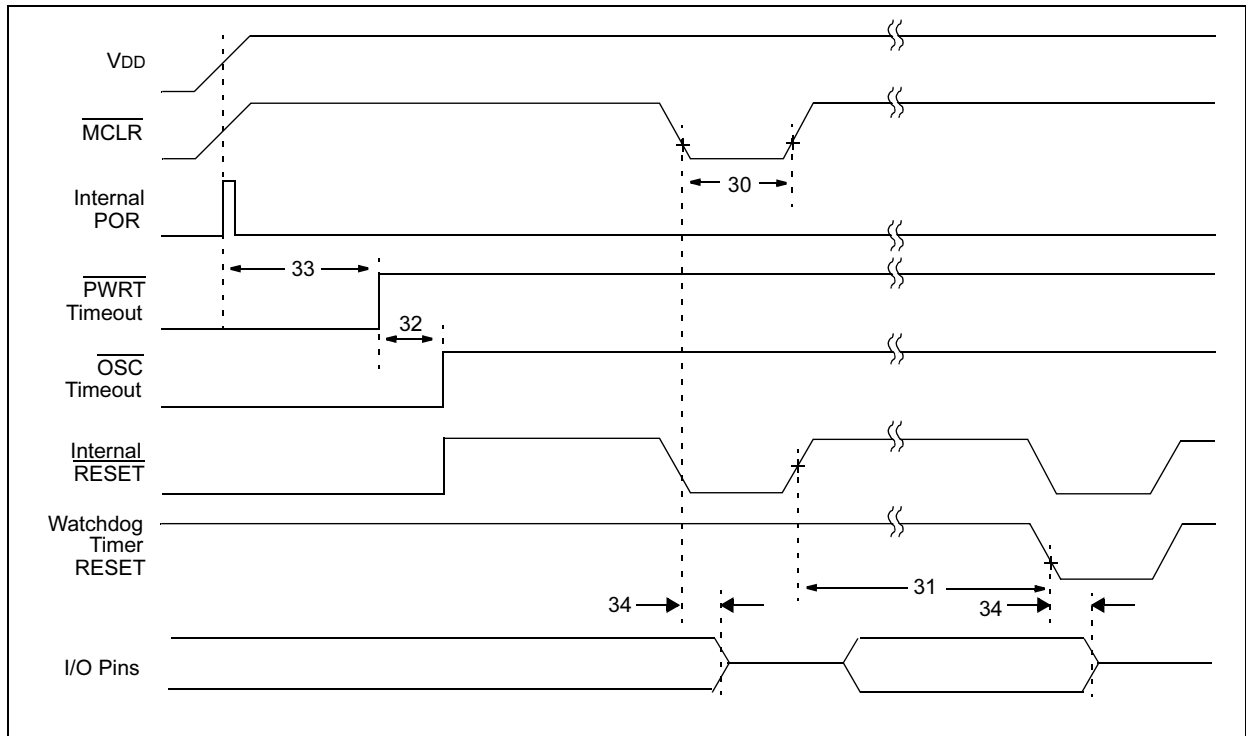
## 12.7 AC Characteristics: PIC16C620A/C621A/C622A-40<sup>(2)</sup> (Commercial) PIC16CR620A-40<sup>(2)</sup> (Commercial)

AC CHARACTERISTICS All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	Sym	Min	Typ <sup>(1)</sup>	Max	Units	Conditions
External CLKIN Frequency	FOSC	20	—	40	MHz	HS mode, OSC1 externally driven
External CLKIN Period	Tosc	25	—	50	ns	HS mode (40), OSC1 externally driven
Clock in (OSC1) Low or High Time	TosL, TosH	6	—	—	ns	HS mode, OSC1 externally driven
Clock in (OSC1) Rise or Fall Time	TosR, TosF	—	—	6.5	ns	HS mode, OSC1 externally driven
OSC1↑ (Q1 cycle) to Port out valid	TosH2ioV	—	—	100	ns	—
OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TosH2ioI	50	—	—	ns	—

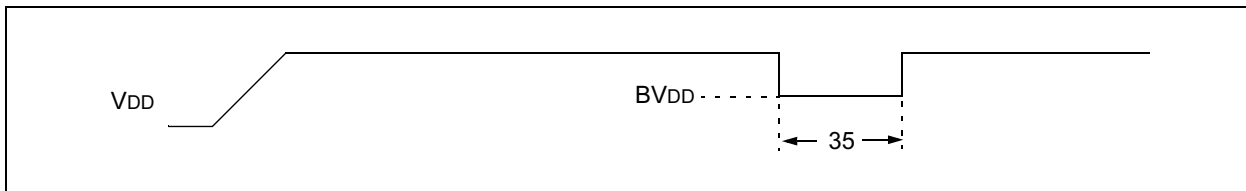
**Note 1:** Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**2:** For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

**FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING**



**FIGURE 12-15: BROWN-OUT RESET TIMING**



**TABLE 12-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	TIOZ	I/O hi-impedance from MCLR low	—	—	2.0	μs	
35	TBOR	Brown-out Reset Pulse Width	100*	—	—	μs	3.7V ≤ VDD ≤ 4.3V

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-5:  $I_{OH}$  vs.  $V_{OH}$ ,  $V_{DD} = 3.0V$

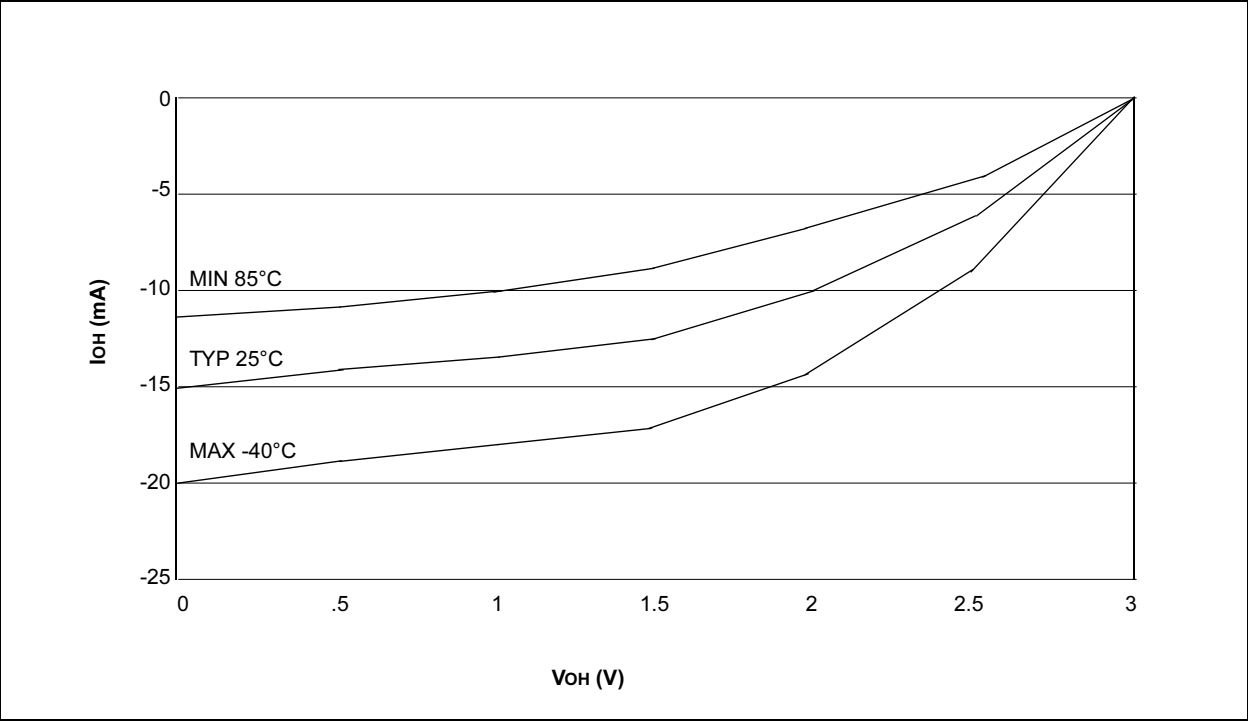
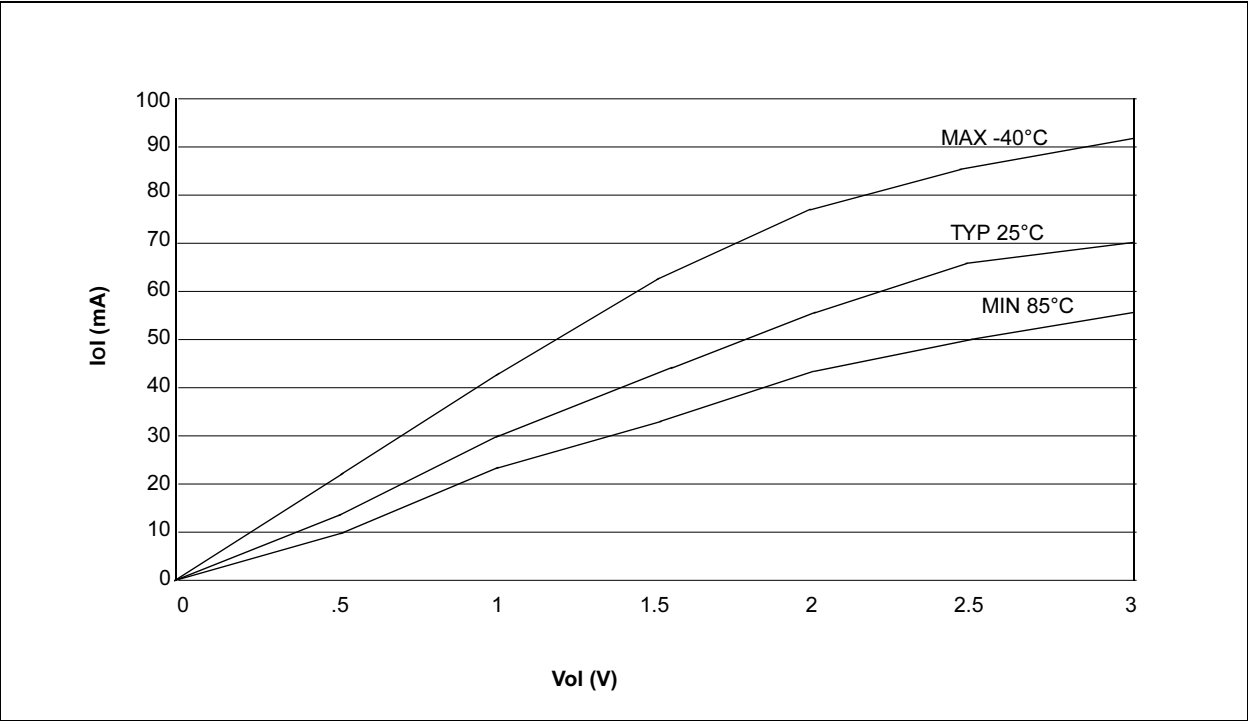
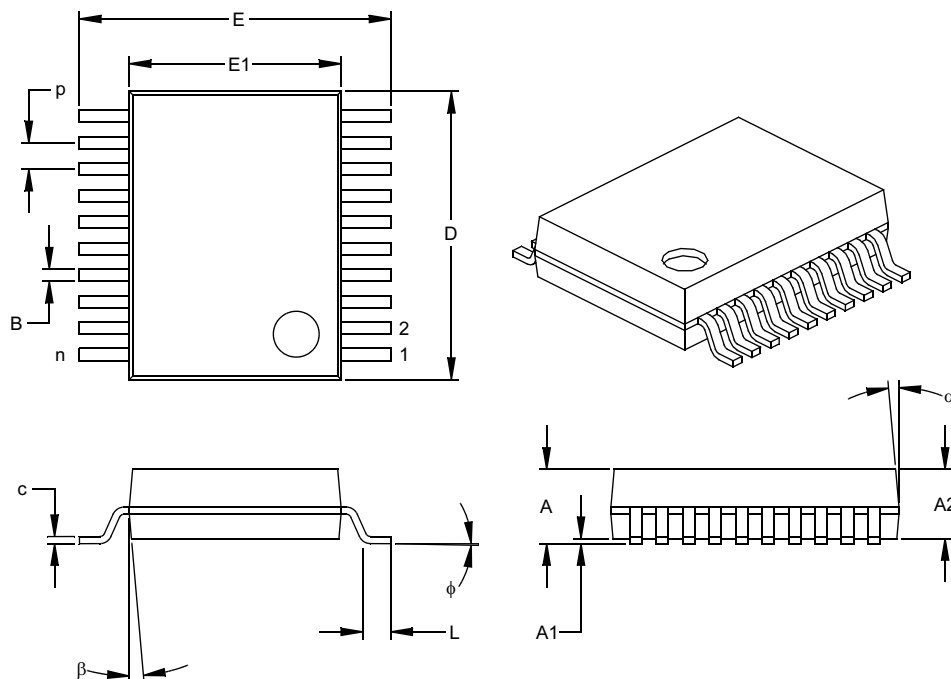


FIGURE 13-6:  $I_{OL}$  vs.  $V_{OL}$ ,  $V_{DD} = 5.5V$



# PIC16C62X

## 20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	phi	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	alpha	0	5	10	0	5	10
Mold Draft Angle Bottom	beta	0	5	10	0	5	10

\* Controlling Parameter

§ Significant Characteristic

### Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

## READER RESPONSE

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Questions:

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2. How does this document meet your hardware and software development needs?

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3. Do you find the organization of this document easy to follow? If not, why?

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4. What additions to the document do you think would enhance the structure and subject?

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5. What deletions from the document could be made without affecting the overall usefulness?

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6. Is there any incorrect or misleading information (what and where)?

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7. How would you improve this document?

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